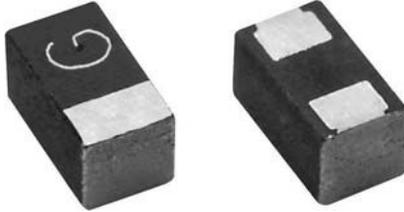


Solid Tantalum Chip Capacitors MICROTAN[®] Low ESR, Leadframeless Molded


FEATURES

- Lead (Pb)-free face-down terminations
- Mounting: Surface mount
- 8 mm tape and reel packaging available per EIA-481 and reeling per IEC 60286-3 7" [178 mm] standard
- Low ESR
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
GREEN
(5-2008)

PERFORMANCE CHARACTERISTICS

Operating Temperature: - 55 °C to + 85 °C
(to + 125 °C voltage derating)

Capacitance Range: 1 µF to 220 µF

Capacitance Tolerance: ± 20 % standard, ± 10 % available

Voltage Range: 4 V_{DC} to 16 V_{DC}

ORDERING INFORMATION						
TR8 TYPE	M CASE CODE	106 CAPACITANCE	M CAPACITANCE TOLERANCE	6R3 DC VOLTAGE RATING AT + 85 °C	C TERMINATION	2000 ESR
	See Ratings and Case Codes table	This is expressed in picofarads. The first two digits are the significant figures. The third is the number of zeros to follow.	K = ± 10 % M = ± 20 %	This is expressed in volts. To complete the three-digit block, zeros precede the voltage rating. A decimal point is indicated by an "R" (6R3 = 6.3 V).	C = 100 % tin 7" [178 mm] reel	Maximum 100 kHz ESR in (mΩ) ⁽¹⁾

Notes

- We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size. Voltage substitutions will be marked with the higher voltage rating.
- (1) The EIA and CECC standards for low ESR solid tantalum chip capacitors, allow delta ESR of 1.25 times the datasheet limit after mounting.

DIMENSIONS in inches [millimeters]						
CASE CODE	L	W	H	P1	P2	C
M	0.063 ± 0.008 [1.60 ± 0.2]	0.033 ± 0.008 [0.85 ± 0.2]	0.031 ± 0.004 [0.80 ± 0.1]	0.020 ± 0.004 [0.50 ± 0.1]	0.024 ± 0.004 [0.60 ± 0.1]	0.024 ± 0.004 [0.60 ± 0.1]
P	0.094 ± 0.004 [2.4 ± 0.1]	0.057 ± 0.004 [1.45 ± 0.1]	0.043 ± 0.004 [1.10 ± 0.1]	0.020 ± 0.004 [0.50 ± 0.1]	0.057 ± 0.004 [1.40 ± 0.1]	0.035 ± 0.004 [0.90 ± 0.1]
Q	0.126 ± 0.008 [3.2 ± 0.2]	0.063 ± 0.008 [1.6 ± 0.2]	0.039 max. [1.0 max.]	0.031 ± 0.004 [0.80 ± 0.1]	0.063 [1.60]	0.047 ± 0.004 [1.20 ± 0.1]

RATINGS AND CASE CODES				
μF	4 V	6.3 V	10 V	16 V
1.0				M
4.7				M
10		M	M	
15			M	
22		M		
33	M	M		
47	M		P	
220	P/Q			

MARKING			
M-Case	P-Case	Q-Case	
VOLTAGE CODE		CAPACITANCE CODE	
V	CODE	CAP, μF	CODE
4.0	G	33	n
6.3	J	47	s
10	A	68	w
16	C	100	Ā
20	D	150	Ē
25	E	220	J

STANDARD RATINGS							
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DC LEAKAGE AT + 25 °C (μA)	MAX. DF AT + 25 °C (%)	MAX. ESR AT + 25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)	ΔC/C ⁽¹⁾ (%)
4 V_{DC} AT + 85 °C; 2.7 V_{DC} AT + 125 °C							
33	M	TR8M336M004C1500	2.6	30	1.50	0.129	± 20
47	M	TR8M476M004C1500	3.8	40	1.50	0.129	± 30
220	P	TR8P227(1)004C1000	17.6	30	1.00	0.212	± 30
220	Q	TR8Q227M004C1200	88.0	80	1.20	0.214	± 30
6.3 V_{DC} AT + 85 °C; 4 V_{DC} AT + 125 °C							
10	M	TR8M106(1)6R3C2000	0.6	8	2.00	0.112	± 10
22	M	TR8M226M6R3C1500	2.8	20	1.50	0.129	± 15
33	M	TR8M336M6R3C1500	4.2	30	1.50	0.129	± 30
10 V_{DC} AT + 85 °C; 7 V_{DC} AT + 125 °C							
10	M	TR8M106M010C2000	1.0	20	2.00	0.112	± 15
15	M	TR8M156(1)010C3000	1.5	30	3.00	0.091	± 20
47	P	TR8P476M010C0800	4.7	22	0.80	0.237	± 20
47	P	TR8P476M010C1000	4.7	22	1.00	0.212	± 20
16 V_{DC} AT + 85 °C; 10 V_{DC} AT + 125 °C							
1.0	M	TR8M105(1)016C9500	0.5	6.0	9.50	0.05	± 15
4.7	M	TR8M475M016C4000	0.8	8.0	4.00	0.08	± 15

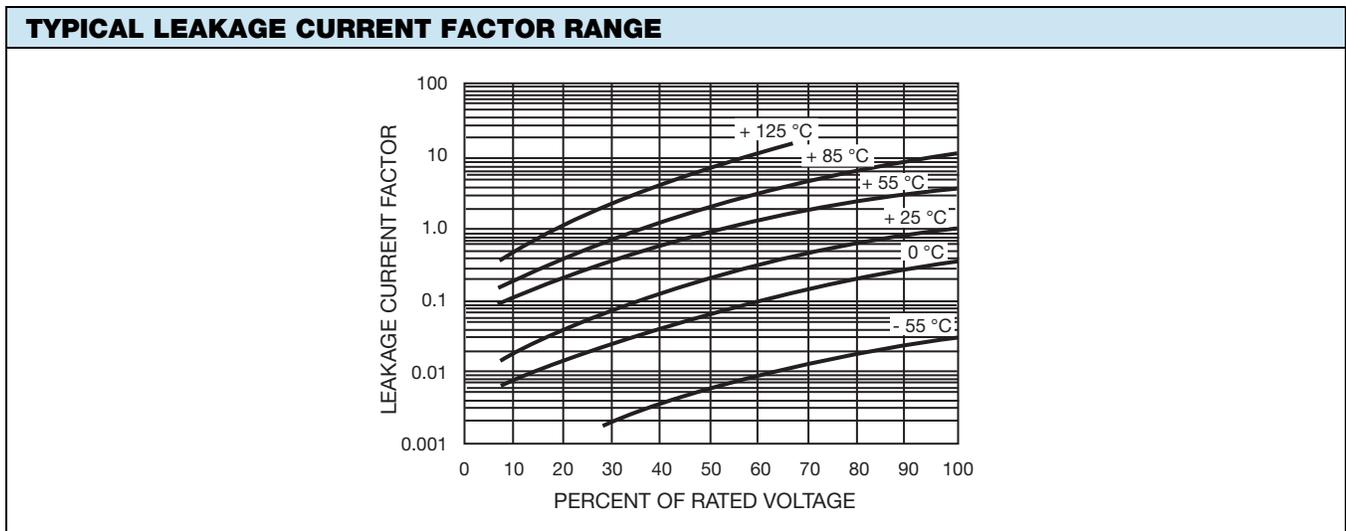
Notes

- Part number definition:
 - (1) Tolerance: For 10 % tolerance, specify "K"; for 20 % tolerance, change to "M"
- (1) See Performance Characteristics tables



CAPACITORS PERFORMANCE CHARACTERISTICS

ELECTRICAL PERFORMANCE CHARACTERISTICS				
ITEM	PERFORMANCE CHARACTERISTICS			
Category Temperature Range	- 55 °C to + 85 °C (to + 125 °C with voltage derating)			
Capacitance Tolerance	± 20 %, ± 10 % (at 120 Hz) 2 V _{RMS} at + 25 °C using a capacitance bridge			
Dissipation Factor (at 120 Hz)	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 120 Hz.			
ESR (100 kHz)	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 100 kHz.			
Leakage Current	After application of rated voltage applied to capacitors for 5 min using a steady source of power with 1 kΩ resistor in series with the capacitor under test, leakage current at 25 °C is not more than described in Standard Ratings table. Note that the leakage current varies with temperature and applied voltage. See graph below for the appropriate adjustment factor.			
Reverse Voltage	Capacitors are capable of withstanding peak voltages in the reverse direction equal to: 10 % of the DC rating at + 25 °C 5 % of the DC rating at + 85 °C Vishay does not recommend intentional or repetitive application of reverse voltage			
Temperature Derating	If capacitors are to be used at temperatures above + 25 °C, the permissible RMS ripple current or voltage shall be calculated using the derating factors: 1.0 at + 25 °C 0.9 at + 85 °C 0.4 at + 125 °C			
Operating Temperature	+ 85 °C RATING		+ 125 °C RATING	
	WORKING VOLTAGE (V)	SURGE VOLTAGE (V)	WORKING VOLTAGE (V)	SURGE VOLTAGE (V)
	4.0	5.2	2.7	3.4
	6.3	8.0	4.0	5.0
	10	13	7.0	8.0
	16	20	10	12
	20	26	13	16
	25	32	17	20
	35	46	23	28
50	65	33	40	



Notes

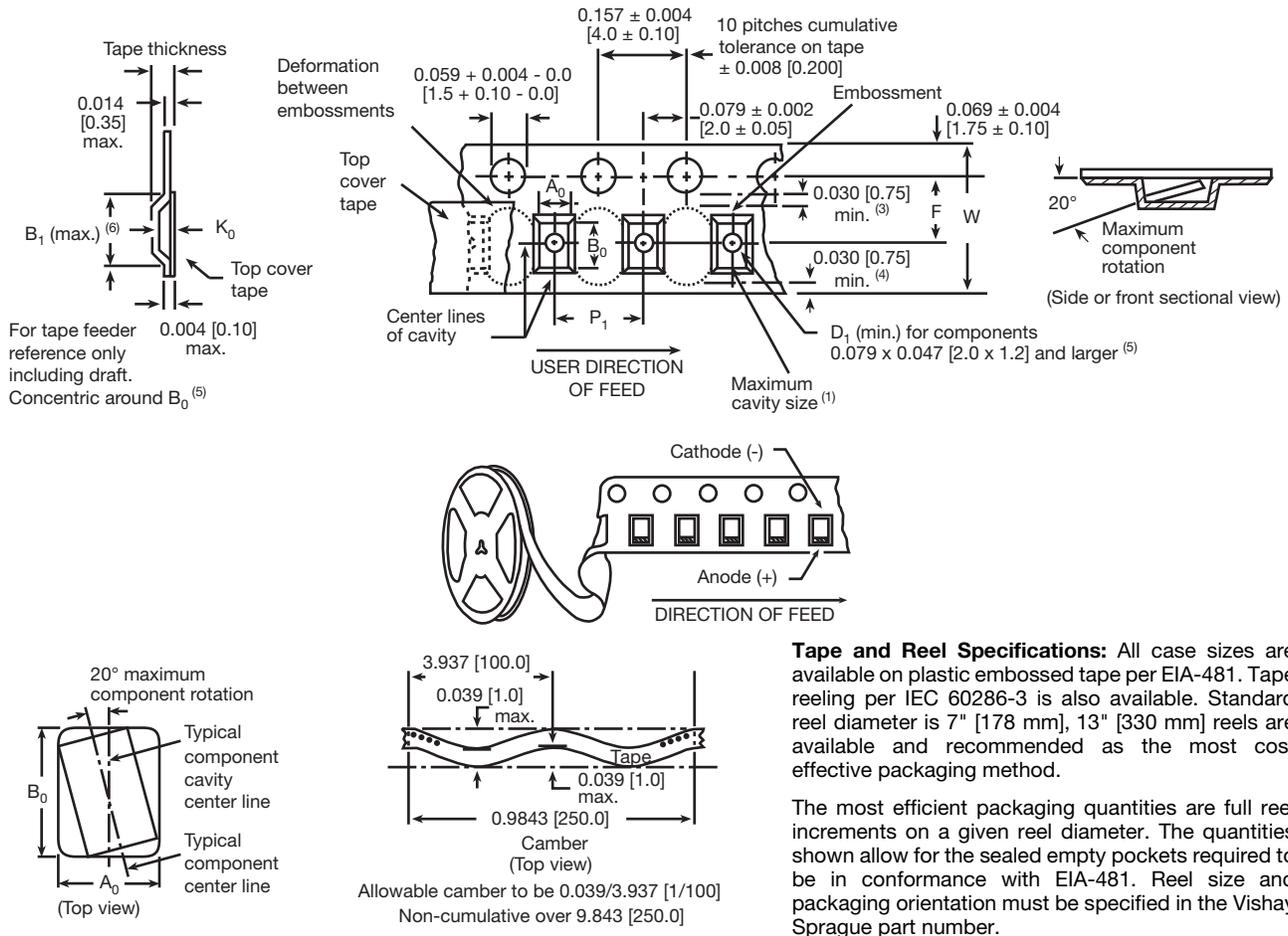
- At + 25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table.
- At + 85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table.
- At + 125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table.



ENVIRONMENTAL PERFORMANCE CHARACTERISTICS			
ITEM	CONDITION	POST TEST PERFORMANCE	
Life Test at + 85 °C	1000 h application of rated voltage at 85 °C with a 3 Ω series resistance, MIL-STD 202G method 108A	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial
Humidity Tests	At 40 °C/90 % RH 500 h, no voltage applied MIL-STD 202G method 103B	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial
Thermal Shock	At - 55 °C/+ 125 °C, 30 min each, for 5 cycles. MIL-STD 202G method 107G	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial

MECHANICAL PERFORMANCE CHARACTERISTICS			
ITEM	CONDITION	POST TEST PERFORMANCE	
Terminal Strength	Apply a pressure load of 5 N for 10 s ± 1 s horizontally to the center of capacitor side body. AEC-Q200 rev. C method 006	Capacitance change Dissipation factor Leakage current There shall be no mechanical or visual damage to capacitors post-conditioning.	Refer to Standard Ratings table Initial specified value or less Initial specified value or less
Substrate Bending (Board Flex)	With parts soldered onto substrate test board, apply force to the test board for a deflection of 1 mm. AEC-Q200 rev. C method 005	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Initial specified value or less Initial specified value or less
Vibration	MIL-STD-202G, method 204D, 10 Hz to 2000 Hz, 20 g Peak	Capacitance change Dissipation factor Leakage current There shall be no mechanical or visual damage to capacitors post-conditioning.	Refer to Standard Ratings table Initial specified value or less Initial specified value or less
Shock	MIL-STD-202G, method 213B, condition I, 100 g peak	Capacitance change Dissipation factor Leakage current There shall be no mechanical or visual damage to capacitors post-conditioning.	Refer to Standard Ratings table Initial specified value or less Initial specified value or less
Resistance to Solder Heat	At 260 °C, for 10 s, reflow	Capacitance change Dissipation factor Leakage current There shall be no mechanical or visual damage to capacitors post-conditioning.	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial
Solderability	MIL-STD-202G, method 208H, ANSI/J-STD-002, Test B. Applies only to solder and tin plated terminations. Does not apply to gold terminations.	There shall be no mechanical or visual damage to capacitors post-conditioning.	
Resistance to Solvents	MIL-STD-202, method 215D	There shall be no mechanical or visual damage to capacitors post-conditioning.	
Flammability	Encapsulation materials meet UL 94 V-0 with an oxygen index of 32 %.		

PLASTIC TAPE AND REEL PACKAGING in inches [millimeters]

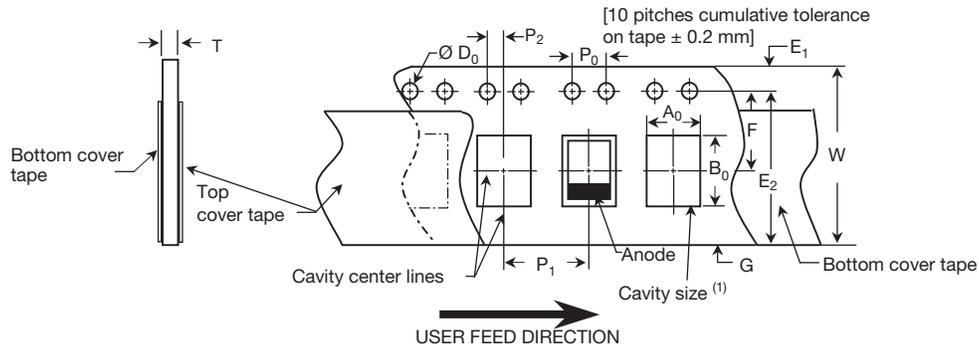


Notes

- Metric dimensions will govern. Dimensions in inches are rounded and for reference only.
- A_0 , B_0 , K_0 , are determined by the maximum dimensions to the ends of the terminals extending from the component body and/or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A_0 , B_0 , K_0) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°.
- Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum.
- This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less.
- This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less.
- The embossed hole location shall be measured from the sprocket hole controlling the location of the embossement. Dimensions of embossement location shall be applied independent of each other.
- B_1 dimension is a reference dimension tape feeder clearance only.

CARRIER TAPE DIMENSIONS in inches [millimeters]

CASE CODE	TAPE SIZE	B_1 (MAX.)	D_1 (MIN.)	F	K_0 (MAX.)	P_1	W
P	8 mm	0.108 [2.75]	0.039 [1.0]	0.138 ± 0.002 [3.5 ± 0.05]	0.054 [1.37]	0.157 ± 0.004 [4.0 ± 1.0]	$0.315 + 0.0118/- 0.0039$ [8.0 + 0.30/- 0.10]
Q	8 mm	0.165 [4.2]	0.039 [1.0]	0.138 ± 0.002 [3.5 ± 0.05]	0.094 [2.4]	0.157 ± 0.004 [4.0 ± 1.0]	0.315 ± 0.012 [8.0 ± 0.30]

PAPER TAPE AND REEL PACKAGING in inches [millimeters]


CASE SIZE	TAPE SIZE	A ₀	B ₀	D ₀	P ₀	P ₁	P ₂	E	F	W	T
M	8 mm	0.041 ± 0.002 [1.05 ± 0.05]	0.071 ± 0.002 [1.8 ± 0.05]	0.06 ± 0.004 [1.5 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.079 ± 0.002 [2.0 ± 0.05]	0.069 ± 0.004 [1.75 ± 0.1]	0.0138 ± 0.002 [3.5 ± 0.05]	0.315 ± 0.008 [8.0 ± 0.2]	0.037 ± 0.002 [0.95 ± 0.05]

Note

(1) A₀, B₀ are determined by the maximum dimensions to the ends of the terminals extending from the component body and/or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°.

STANDARD PACKAGING QUANTITY

CASE CODE	QUANTITY (PCS/REEL)
	7" REEL
M	4000
P	3000
Q	2500

RECOMMENDED VOLTAGE DERATING GUIDELINES
STANDARD CONDITIONS. FOR EXAMPLE: OUTPUT FILTERS

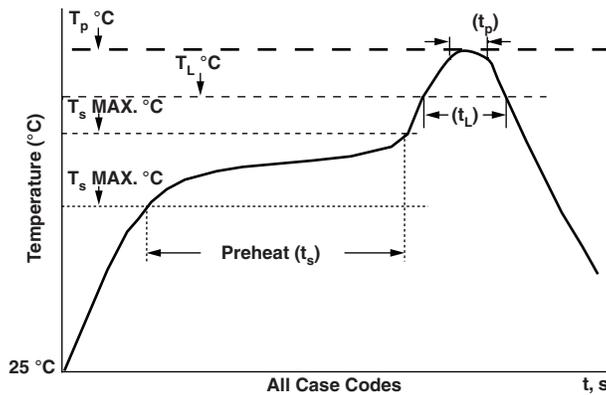
Capacitor Voltage Rating	Operating Voltage
4.0	2.5
6.3	3.6
10	6.0
16	10
20	12
25	15
35	24
50	28

SEVERE CONDITIONS. FOR EXAMPLE: INPUT FILTERS

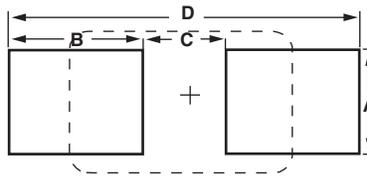
Capacitor Voltage Rating	Operating Voltage
4.0	2.5
6.3	3.3
10	5.0
16	8.0
20	10
25	12
35	15
50	24

POWER DISSIPATION

CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT + 25 °C (W) IN FREE AIR
M	0.025
P	0.045
Q	0.055

RECOMMENDED REFLOW PROFILES


T_P lead (Pb)-free	T_P Sn/Pb	t_P	T_L lead (Pb)-free	T_L Sn/Pb	T_S MIN. lead (Pb)-free	T_S MIN. Sn/Pb	T_S MAX. lead (Pb)-free	t_S MAX. Sn/Pb	t_S lead (Pb)-free	T_S Sn/Pb	t_L
260 °C	225 °C	10	217 °C	183 °C	150 °C	100 °C	200 °C	150 °C	60 to 150	60 to 90	60

PAD DIMENSIONS in inches [millimeters]


CASE CODE	A (MIN.)	B (NOM.)	C (NOM.)	D (NOM.)
M	0.039 [1.00]	0.028 [0.70]	0.024 [0.60]	0.080 [2.00]
P	0.063 [1.60]	0.031 [0.80]	0.047 [1.20]	0.110 [2.80]
Q	0.071 [1.80]	0.067 [1.70]	0.053 [1.35]	0.187 [4.75]



GUIDE TO APPLICATION

1. AC Ripple Current: The maximum allowable ripple current shall be determined from the formula:

I_RMS = sqrt(P / R_ESR)

where,

P = Power dissipation in watts at + 25 °C (see paragraph number 5 and the table Power Dissipation)

R_ESR = The capacitor equivalent series resistance at the specified frequency

2. AC Ripple Voltage: The maximum allowable ripple voltage shall be determined from the formula:

V_RMS = Z * sqrt(P / R_ESR)

or, from the formula:

V_RMS = I_RMS * Z

where,

P = Power dissipation in watts at + 25 °C (see paragraph number 5 and the table Power Dissipation)

R_ESR = The capacitor equivalent series resistance at the specified frequency

Z = The capacitor impedance at the specified frequency

2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.

2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at + 25 °C.

3. Reverse Voltage: These capacitors are capable of withstanding peak voltages in the reverse direction equal to 10 % of the DC rating at + 25 °C, 5 % of the DC rating at + 85 °C and 1 % of the DC rating at + 125 °C.

4. Temperature Derating: If these capacitors are to be operated at temperatures above + 25 °C, the permissible RMS ripple current or voltage shall be calculated using the derating factors as shown:

Table with 2 columns: TEMPERATURE and DERATING FACTOR. Rows: + 25 °C (1.0), + 85 °C (0.9), + 125 °C (0.4)

5. Power Dissipation: Power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_RMS value be established when calculating permissible operating levels. (Power Dissipation calculated using + 25 °C temperature rise.)

6. Printed Circuit Board Materials: Molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelainized steel).

7. Attachment:

7.1 Solder Paste: The recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.

7.2 Soldering: Capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering and hot plate methods. The Soldering Profile charts show recommended time/temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 2 °C per s. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.

7.2.1 Backward and Forward Compatibility: Capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.

8. Cleaning (Flux Removal) After Soldering: Molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC/ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.

8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. Do not exceed 9W/I at 40 kHz for 2 min.

9. Recommended Mounting Pad Geometries: Proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and/or circuit board design.

Table with 2 columns: PRODUCT INFORMATION and URL. Rows: Moisture Sensitivity (www.vishay.com/doc?40135), SELECTOR GUIDES, Solid Tantalum Selector Guide (www.vishay.com/doc?49053), Solid Tantalum Chip Capacitors (www.vishay.com/doc?40091), FAQ, Frequently Asked Questions (www.vishay.com/doc?40110)



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.